

REMARKS

This is in response to the Final Rejection of the pending claims in the Office Action mailed August 2, 2006.

Claims 1 through 3, 5, 6, 8 through 20, 22, 23, 25 through 34 are currently pending in the application.

Claims 9 through 17 and 26 through 34 are withdrawn from consideration.

Claims 1 through 3, 5, 6, 18 through 20, 22, 23, and 25 stand rejected. Applicants propose to amend claims 1 and 18, and respectfully request reconsideration of the application as proposed to be amended herein.

35 U.S.C. § 102(b) Anticipation Rejections

Anticipation Rejection Based on U.S. Patent 5,655,704 to Sakemi et al.

Claims 1 through 3, 5, 6, 8, 18 through 20, 22, 23 and 25 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Sakemi et al. (U.S. Patent 5,655,704). Applicants respectfully traverse this rejection, as hereinafter set forth.

Applicants assert that a claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference.

Verdegaal Brothers v. Union Oil Co. of California, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

After carefully considering the cited prior art, the rejections, and the Examiner's comments, Applicants have amended the claimed invention to clearly distinguish over the cited prior art.

Turning to the cited prior art, the Sakemi et al. reference describes a solder ball mounting apparatus using a template 4 to position solder balls 3 from a hopper 12 onto pads 2a of a substrate 2. The substrate 2 only having a plurality of electrodes 2a above the surface of the substrate 2, not having any electrodes whatsoever recessed into the surface of the substrate 2. There is no teaching or suggestion in the Sakemi et al. reference to dispense solder paste from the hopper 12 into or through a template 4 onto the substrate 2. There is no description whatsoever

in the Sakemi et al. reference for dispensing solder balls 3 onto electrodes 2a located in recesses or level surfaces of the substrate 2. The Sakemi et al. reference clearly describes solely the placement of solder balls 3 on the curved surfaces of the electrodes 2a which are neither level nor recessed.

Applicants assert that the Sakemi et al. reference does not anticipate the claimed invention of presently amended independent claims 1 and 18 under 35 U.S.C. § 102 because, at the least, the Sakemi et al. reference fails to identically describe, either expressly or inherently, each and every element of the claimed inventions in as complete detail as contained in the claims. Applicants assert that the Sakemi et al. reference fails to teach or suggest the claim limitations of presently amended independent claims 1 and 18 calling for “a hopper, said hopper having a bottom opening having a dimension extending across said first pattern for dispensing said spheres into said plurality of through-holes extending across said stencil plate, the bottom opening having width in the range of about two diameters of a conductive sphere to about ten diameters of a conductive sphere, said hopper having a bottom lower surface spaced from an upper surface of the stencil plate a distance in the range of about less than one-half the diameter of a conductive sphere to about less than one-third the diameter of a conductive sphere”. “a positioning apparatus for moving said hopper over said pattern relative said stencil plate to place said spheres into said plurality of through-holes onto one of the recessed sites and level sites of said surface of said substrate”, and “a positioning apparatus for moving said hopper over said pattern relative of said stencil plate to position said spheres into said plurality of through-holes onto one of the recessed sites and level sites of said proximate surface of said substrate”.

Applicants assert that the Sakemi et al. reference contains no description whatsoever regarding such elements of the claims. Applicants assert that the Sakemi et al. reference solely describes the placement of solder balls 3 on the curved surfaces of the electrodes 2a which are neither level nor recessed. Therefore, such prior art cannot anticipate the claimed inventions of presently amended independent claims 1 and 18 under 35 U.S.C. § 102. Accordingly, presently amended independent claims 1 and 18 are allowable as well as dependent claims 2, 3 5, 6, 8, 19, 20, and 22 through 25 therefrom.

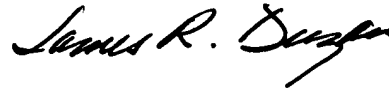
ENTRY OF AMENDMENTS

The proposed amendments to claims 1 and 18 above should be entered by the Examiner because the amendments are supported by the as-filed specification and drawings and do not add any new matter to the application under 35 U.S.C. § 132. Further, the amendments do not raise new issues or require a further search as the claim limitations of amended independent claims 1 and 18 were clearly considered in the Final Rejection of the previous pending claims. Finally, if the Examiner determines that the amendments do not place the application in condition for allowance, entry is respectfully requested upon filing of a Notice of Appeal herein.

CONCLUSION

Claims 1 through 3, 5, 6, 18 through 20, 22, 23, and 25 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, he is respectfully invited to contact Applicants' undersigned attorney.

Respectfully submitted,



James R. Duzan
Registration No. 28,393
Attorney for Applicants
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: September 28, 2006

JRD/sfc:lmh

Document in ProLaw